



Complementary 20 V (D-S) Low-Threshold MOSFET

PRODUCT SUMMARY						
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)			
		0.280 at V _{GS} = 4.5 V	1.28			
N-Channel	20	0.360 at V _{GS} = 2.5 V	1.13			
		0.450 at V _{GS} = 1.8 V	1.00			
P-Channel	- 20	0.490 at V _{GS} = - 4.5 V	- 1.00			
		0.750 at V _{GS} = - 2.5 V	- 0.81			
		1.10 at V _{GS} = - 1.8 V	- 0.67			

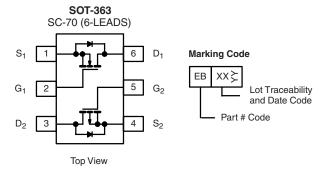
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFETs: 1.8 V Rated
- Thermally Enhanced SC-70 Package
- Fast Switching
- Compliant to RoHS Directive 2002/95/EC



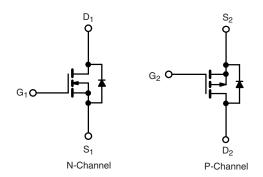
APPLICATIONS

· Load Switch for Portable Devices



Ordering Information: Si1563DH-T1-E3 (Lead (Pb)-free)

Si1563DH-T1-GE3 (Lead (Pb)-free and Halogen-free)



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
Parameter			N-Channel		P-Channel			
		Symbol	5 s	Steady State	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	20		- 20		V	
Gate-Source Voltage		V _{GS}	± 8		± 8		V	
Continuous Dunin Comment /T 450 °C\d	T _A = 25 °C	- I _D	1.28	1.13	- 1.00	- 0.88	^	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 85 °C		0.92	0.81	- 0.72	- 0.63		
Pulsed Drain Current		I _{DM}	4.0		- 3.0		Α	
Continuous Source Current (Diode Conduction) ^a		I _S	0.61	0.48	- 0.61	- 0.48		
Maniana Banas Biasia dia d	T _A = 25 °C	P _D	0.74	0.57	0.30	0.57	W	
Maximum Power Dissipation ^a	T _A = 85 °C		0.38	0.30	0.16	0.3		
Operating Junction and Storage Temperature Range		T _J , T _{sta}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^a	t ≤ 5 s	- R _{thJA}	130	170			
Maximum Junction-to-Ambient	Steady State		170	220	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	80	100			

Notes:

a. Surface mounted on 1" x 1" FR4 board.



SPECIFICATIONS T _J = 25 °C, unless otherwise noted									
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit			
Static	•								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 100 \mu A$ N-		0.45		1	V		
		$V_{DS} = V_{GS}, I_{D} = -100 \mu A$	P-Ch	- 0.45		1	V		
Onto Body London	I _{GSS}	V 0VV .0V	N-Ch			± 100	nA		
Gate-Body Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	P-Ch			± 100			
	I _{DSS}	V _{DS} = 16 V, V _{GS} = 0 V	N-Ch			1			
Zara Cata Valtaga Drain Current		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1	μА		
Zero Gate Voltage Drain Current		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	N-Ch			5			
		$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$	P-Ch			- 5			
On-State Drain Current ^a	l _{ac} ,	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	2			А		
On State Brain Surrent	I _{D(on)}	$V_{DS} \le$ - 5 V, $V_{GS} =$ - 4.5 V	P-Ch	- 2					
		$V_{GS} = 4.5 \text{ V}, I_D = 1.13 \text{ A}$	N-Ch		0.220	0.280			
	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -0.88 \text{ A}$	P-Ch		0.400	0.490	Ω		
Drain-Source On-State Resistance ^a		$V_{GS} = 2.5 \text{ V}, I_D = 0.99 \text{ A}$	N-Ch		0.281	0.360			
Brain Godice on Glate Hesistance		$V_{GS} = -2.5 \text{ V}, I_D = -0.71 \text{ A}$	P-Ch		0.610	0.750			
		$V_{GS} = 1.8 \text{ V}, I_D = 0.20 \text{ A}$	N-Ch		0.344	0.450			
		$V_{GS} = -1.8 \text{ V}, I_D = -0.20 \text{ A}$	P-Ch		0.850	1.10			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 1.13 \text{ A}$	N-Ch		2.6		S		
1 of ward Transconductance		$V_{DS} = -10 \text{ V}, I_{D} = -0.88 \text{ A}$	P-Ch		1.5				
Diode Forward Voltage ^a	V _{SD}	I _S = 0.48 A, V _{GS} = 0 V	N-Ch		0.8	1.2	V		
-		I _S = - 0.48 A, V _{GS} = 0 V P-Ch			- 0.8	- 1.2	V		
Dynamic ^b									
Total Gate Charge	Qg	N Channal	N-Ch		1.25	2	nC		
Total Gate Charge		N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1.13 \text{ A}$	P-Ch		1.2	1.8			
Gate-Source Charge	Q_{gs}		N-Ch		0.21				
		P-Channel $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -0.88$	P-Ch		0.3				
Gate-Drain Charge	Q _{gd}	A A	N-Ch		0.3				
Gate Brain Gridige			P-Ch		0.21				
Turn-On Delay Time	t _{d(on)}		N-Ch		15	25			
		N-Channel	P-Ch		18	30	ns		
Rise Time		$V_{DD} = 10 \text{ V}, R_L = 20 \Omega$	N-Ch		22	35			
		$I_D \cong 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$	P-Ch		25	40			
Turn-Off Delay Time	t _{d(off)}	P-Channel	N-Ch		25	40			
		$V_{DD} = -10 \text{ V}, R_L = 20 \Omega$	P-Ch		15	25			
Fall Time	t _f	$I_D \cong -0.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 6 \Omega$	N-Ch		12	20			
			P-Ch		12	20			
Reverse Recovery Time	t _{rr}	I _F = 0.48 A, dl/dt = 100 A/μs	N-Ch		30	60			
	11	F 55., 2.00.	P-Ch		30	60			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

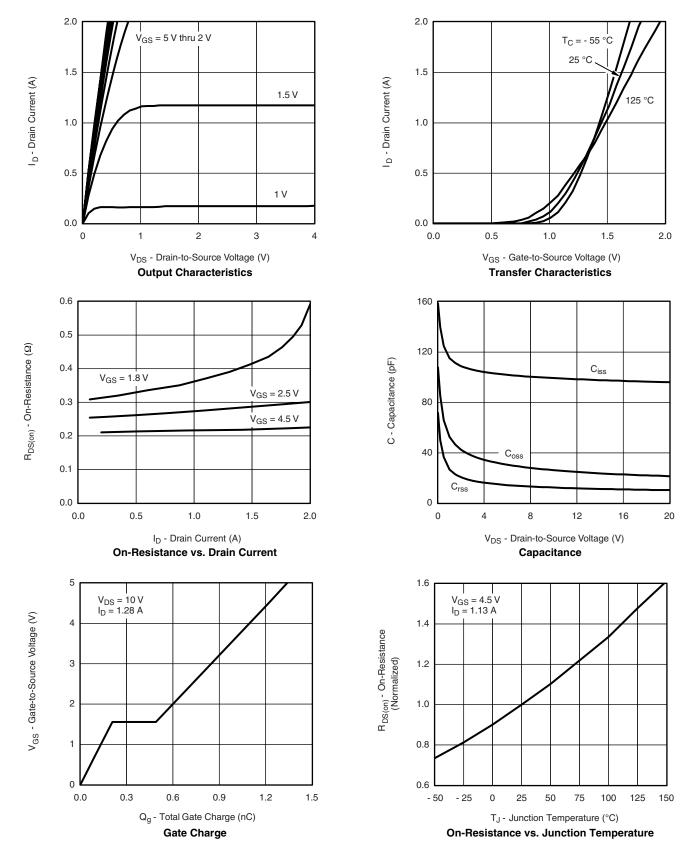
b. Guaranteed by design, not subject to production testing.





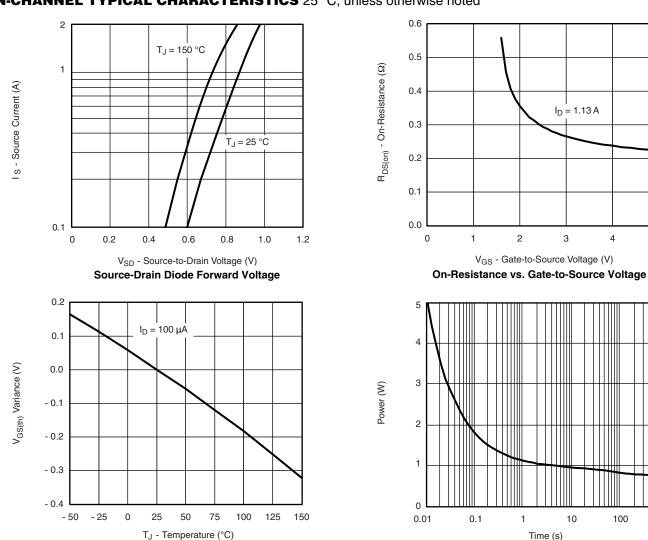


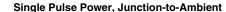
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



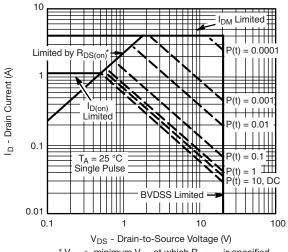
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Threshold Voltage





600

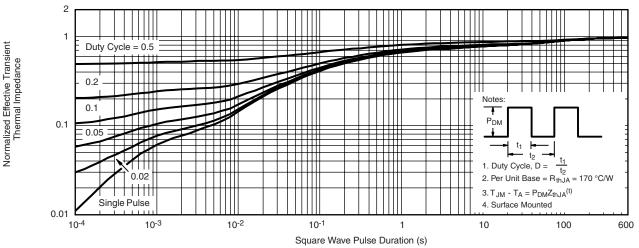


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

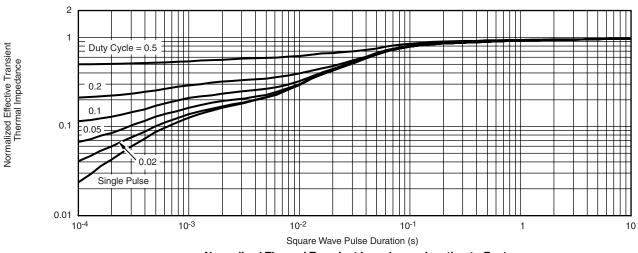
Safe Operating Area, Junction-to-Ambient



N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



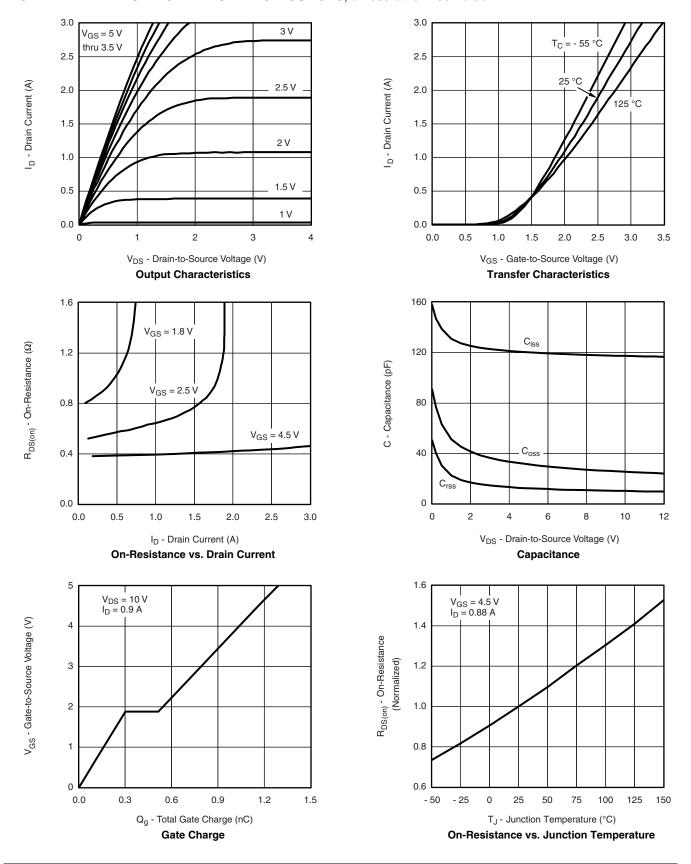
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

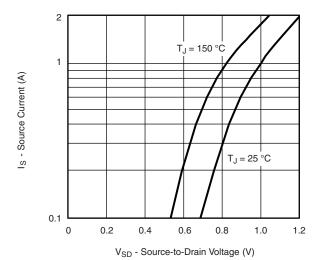








P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





On-Resistance vs. Gate-to-Source Voltage

 $I_D = 0.88 A$

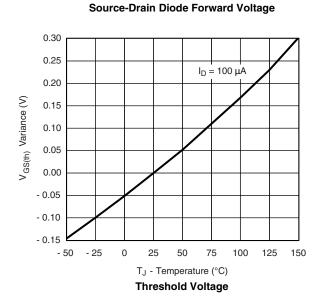
1.6

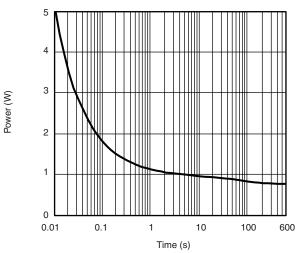
1.2

0.8

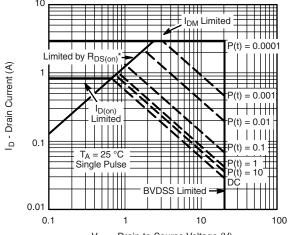
0.4

R_{DS(on)} - On-Resistance (Ω)





Single Pulse Power, Junction-to-Ambient

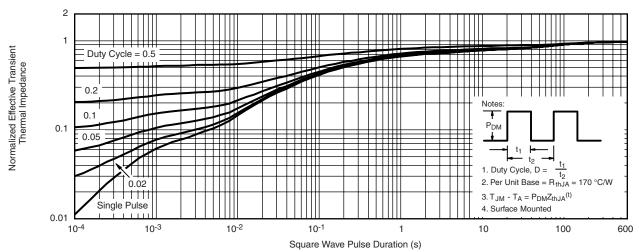


 $$V_{DS}$$ - Drain-to-Source Voltage (V) $$^*\ V_{GS}$$ > minimum V_{GS} at which $R_{DS(on)}$ is specified

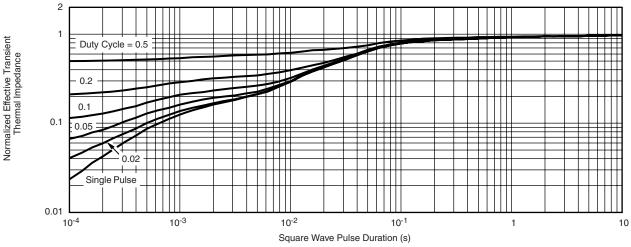
Safe Operating Area, Junction-to-Ambient



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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